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(12) **United States Design Patent**  
**Mori et al.**

(10) **Patent No.:** **US D988,147 S**  
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- (54) **COMPOSITE SENSOR**
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(Continued)

- (\*\*) Term: **15 Years**
- (21) Appl. No.: **29/798,367**
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 PC

(30) **Foreign Application Priority Data**

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- (51) **LOC (14) Cl.** ..... **10-04**
- (52) **U.S. Cl.**  
USPC ..... **D10/46**

- (58) **Field of Classification Search**  
USPC ..... D10/81, 70, 91, 64, 46, 100, 83-89, 50,  
D10/52, 53, 56, 96, 104.1, 104.2, 106.1,  
D10/121  
CPC .... B60R 2001/1223; B60R 2300/8093; B60R  
16/023; B60R 2300/8066; G01K 1/08  
See application file for complete search history.

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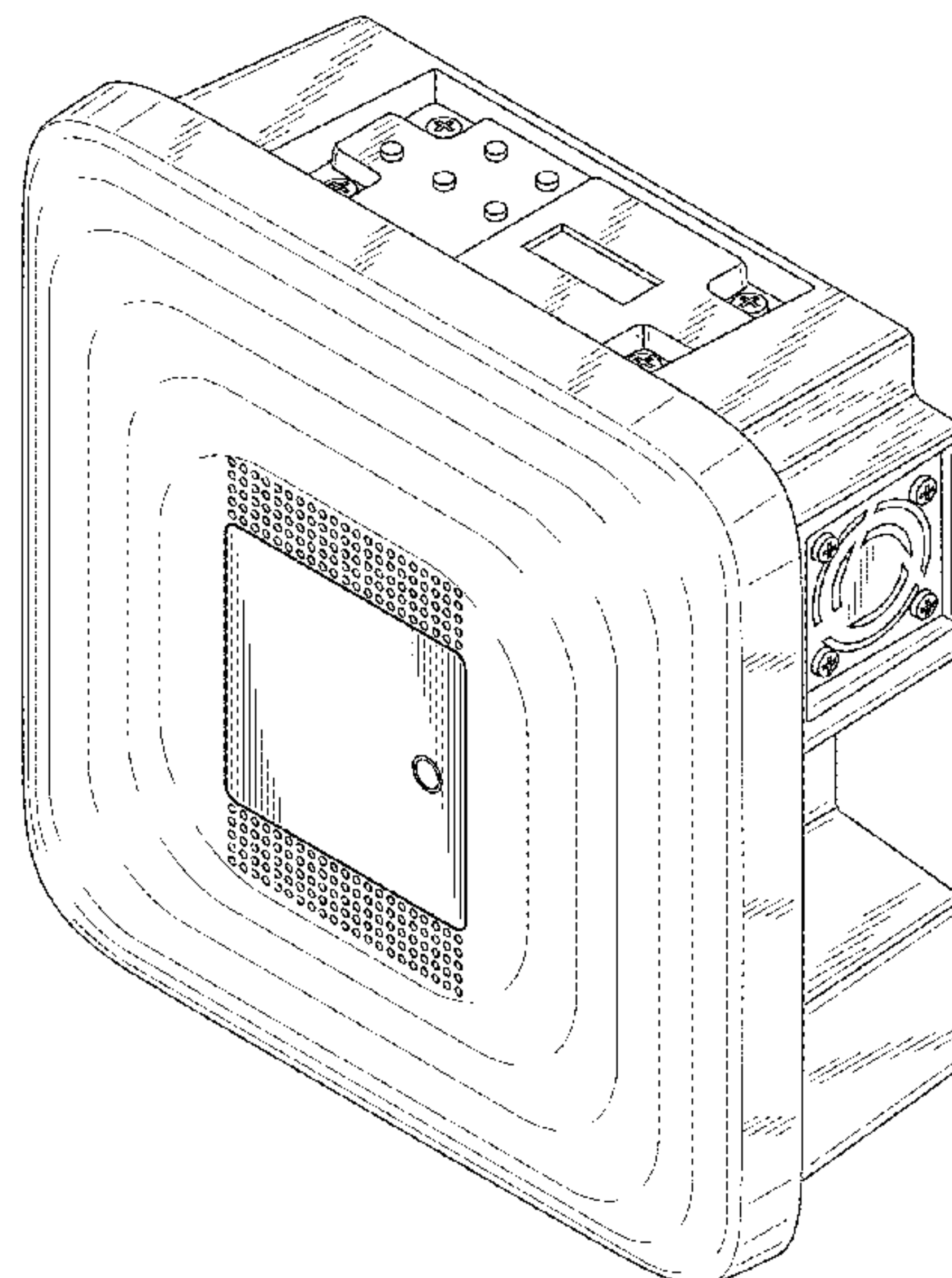
(57) **CLAIM**

The ornamental design for a composite sensor, as shown and described.

**DESCRIPTION**

FIG. 1 is a first perspective view of the front, top, and right sides of a composite sensor showing our new design;  
 FIG. 2 is a second perspective view of the rear, bottom, and left sides thereof;  
 FIG. 3 is a front view thereof;  
 FIG. 4 is a rear view thereof;  
 FIG. 5 is a top plan view thereof;  
 FIG. 6 is a bottom view thereof;  
 FIG. 7 is a right side view thereof;  
 FIG. 8 is a left side view thereof;  
 FIG. 9 is an enlarged view of a part 9-9 in FIG. 3; and,  
 FIG. 10 is an enlarged cross-sectional view taken along line 10-10 of FIG. 9 at area of 10-10 in FIG. 7.  
 The dash-dash broken lines depict portions of the article that form no part of the claimed design. The dot-dash broken lines disclose boundaries of enlarged views and form no part of the claimed design.

**1 Claim, 10 Drawing Sheets**



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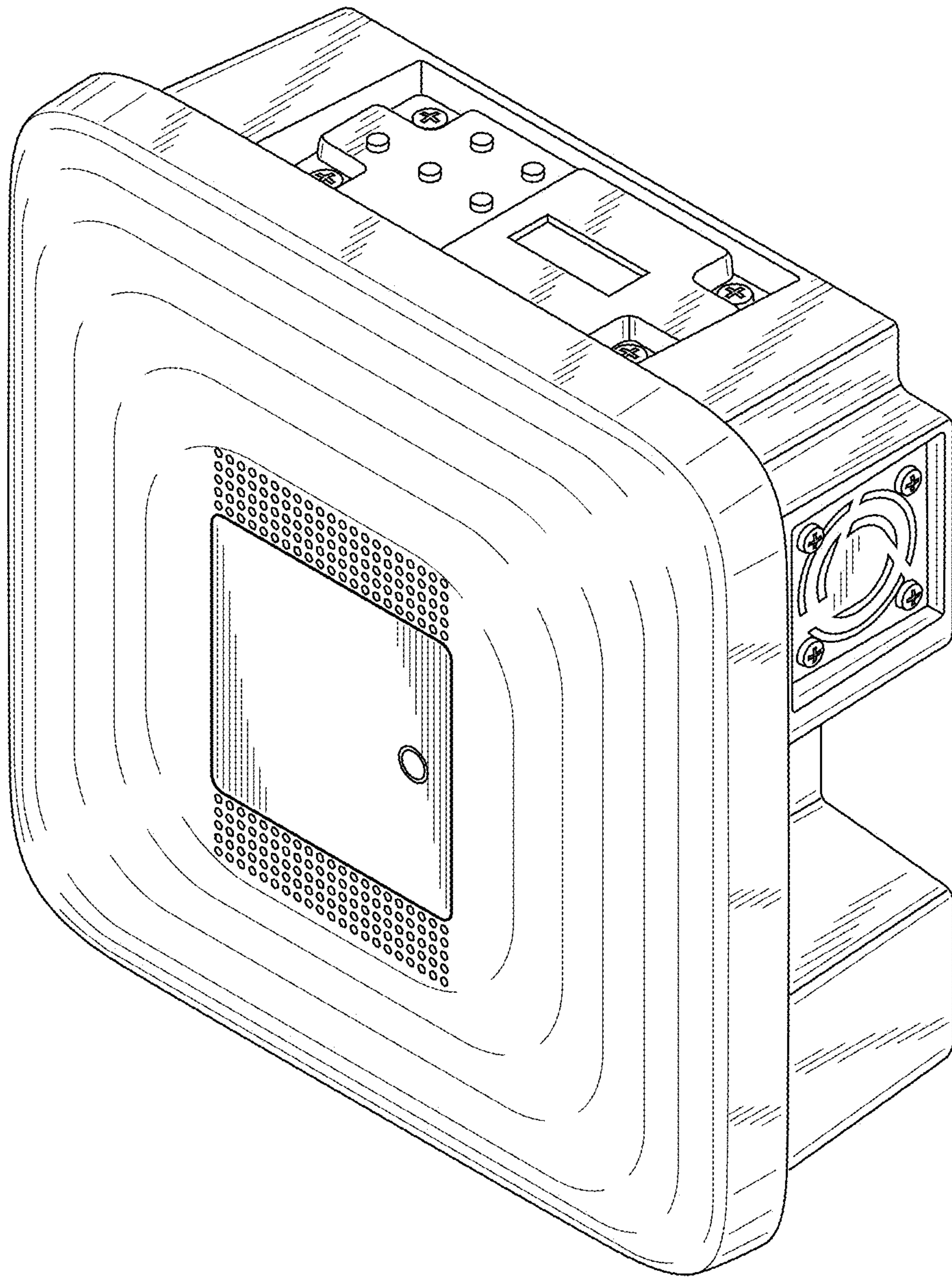
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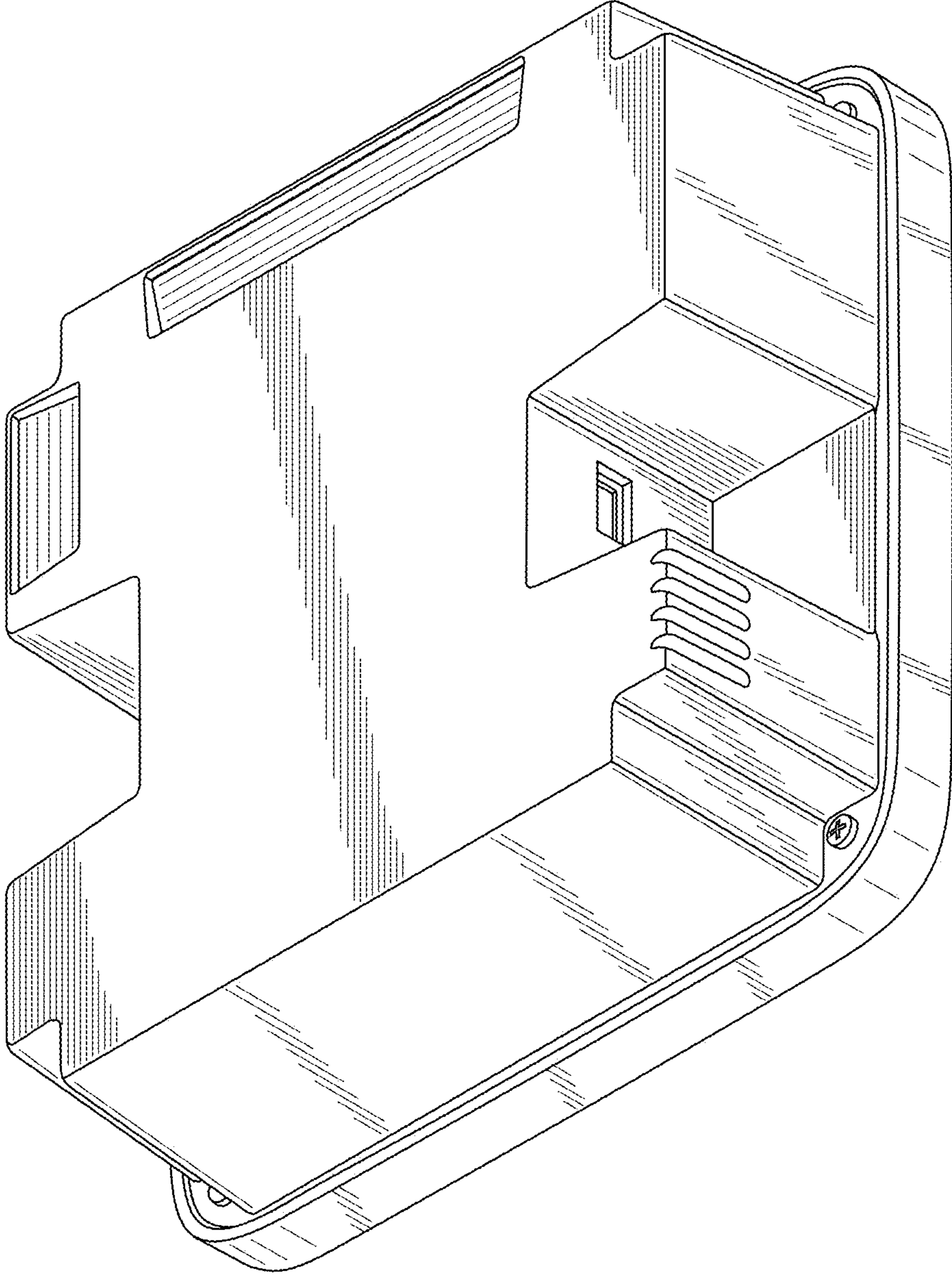
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**FIG. 1**

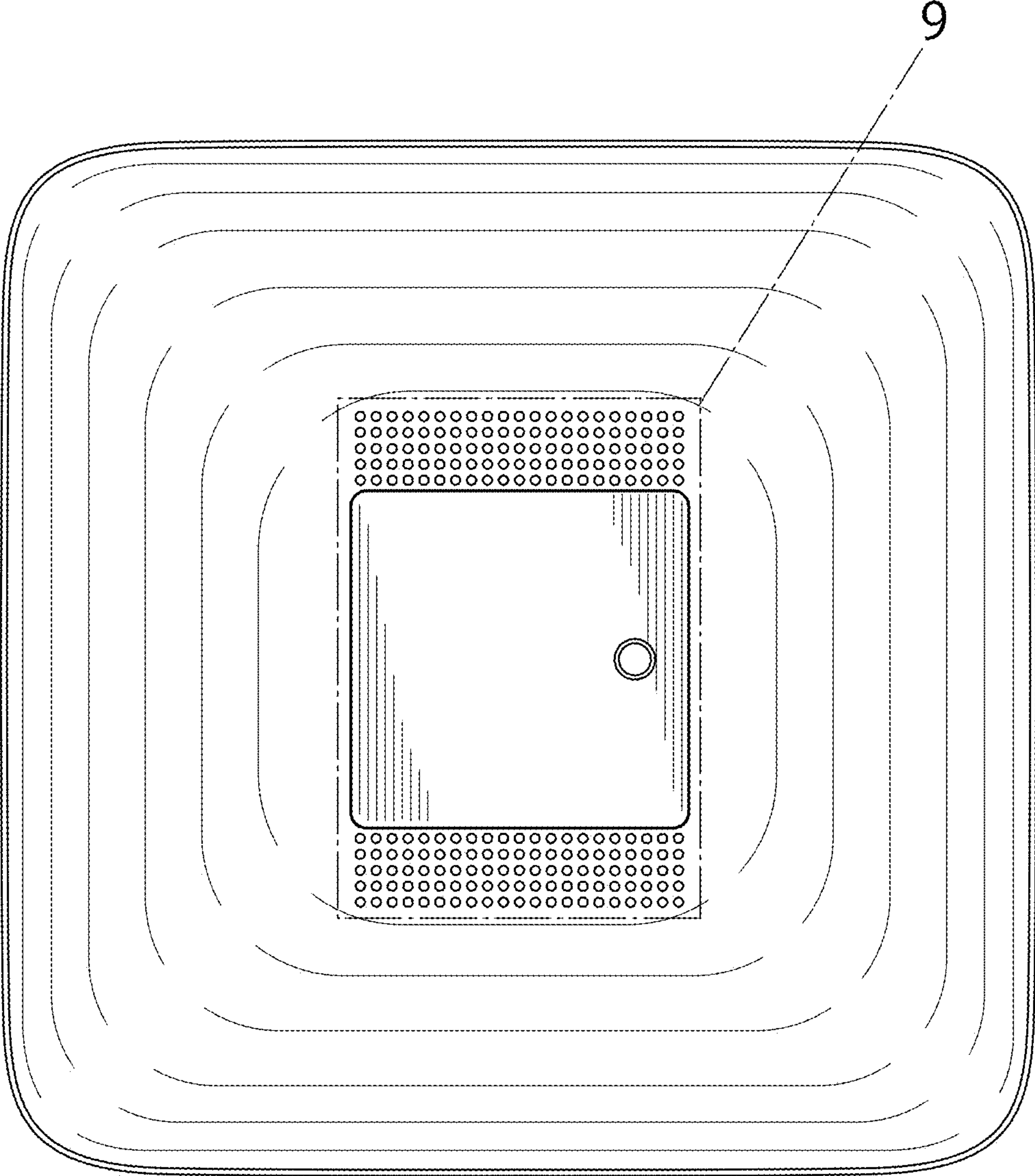




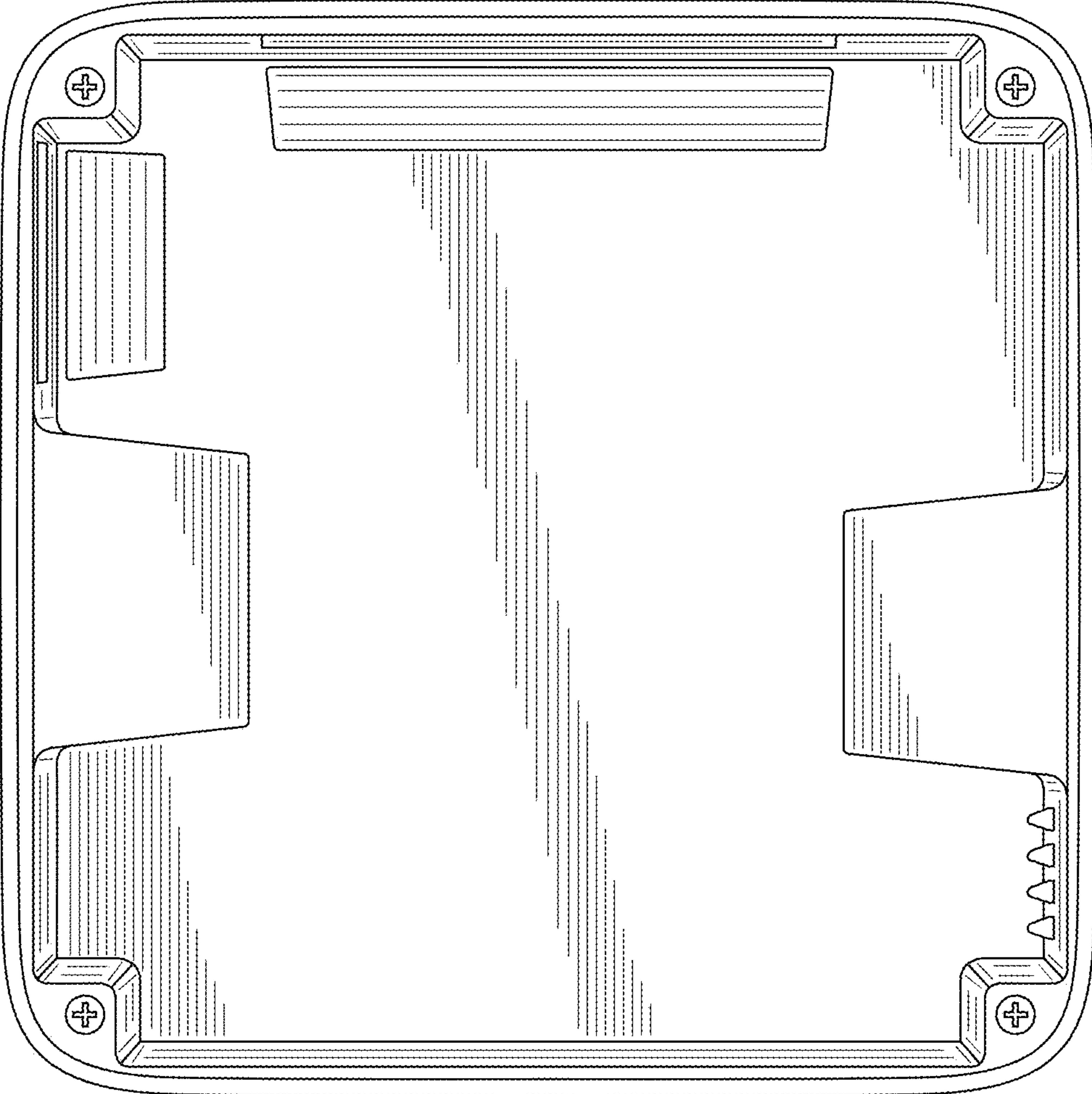
**FIG. 2**



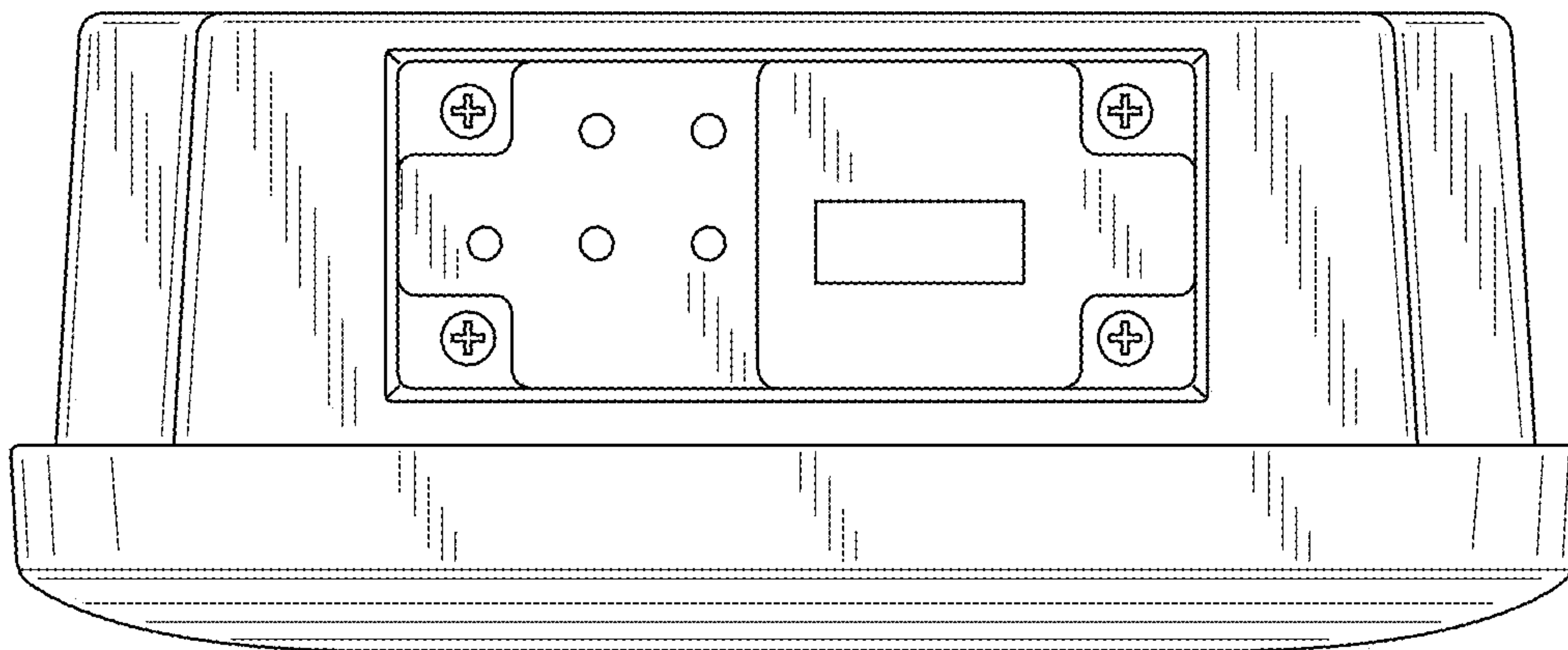
**FIG. 3**



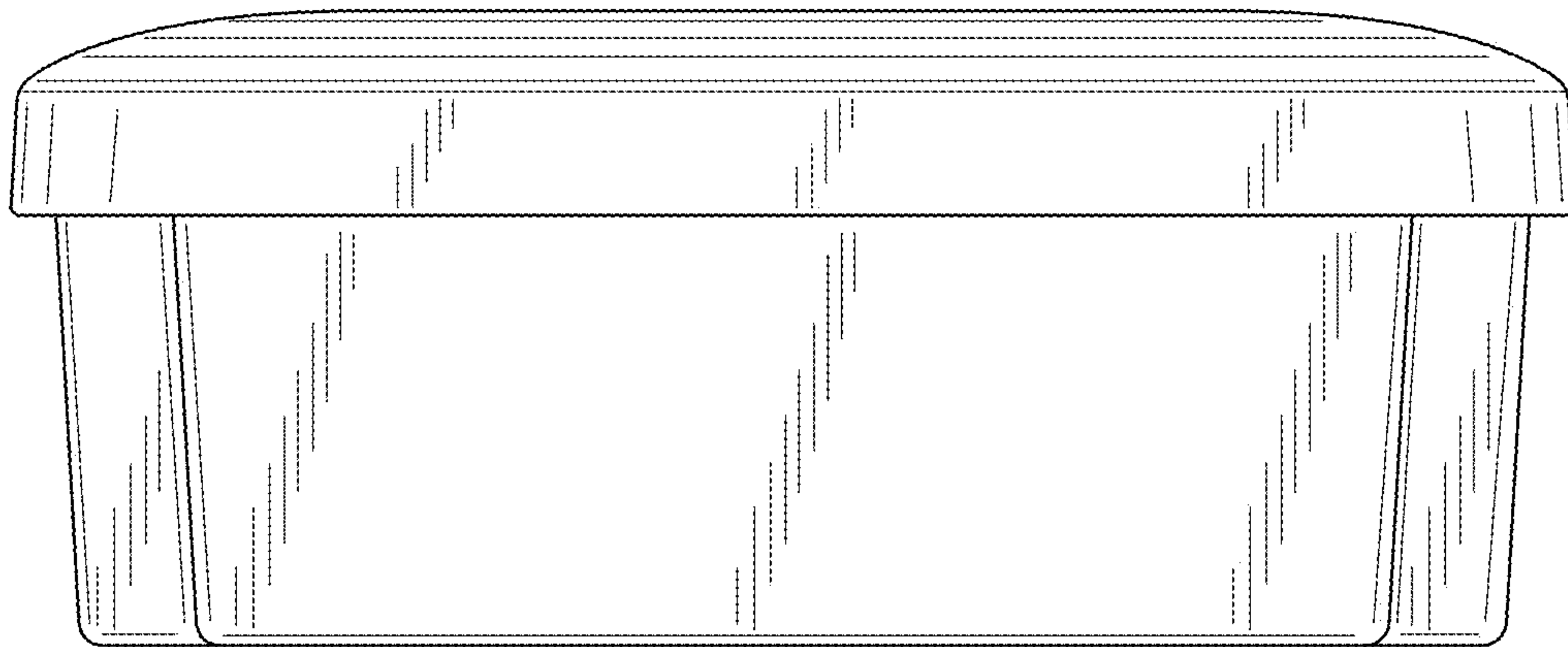
**FIG. 4**



**FIG. 5**

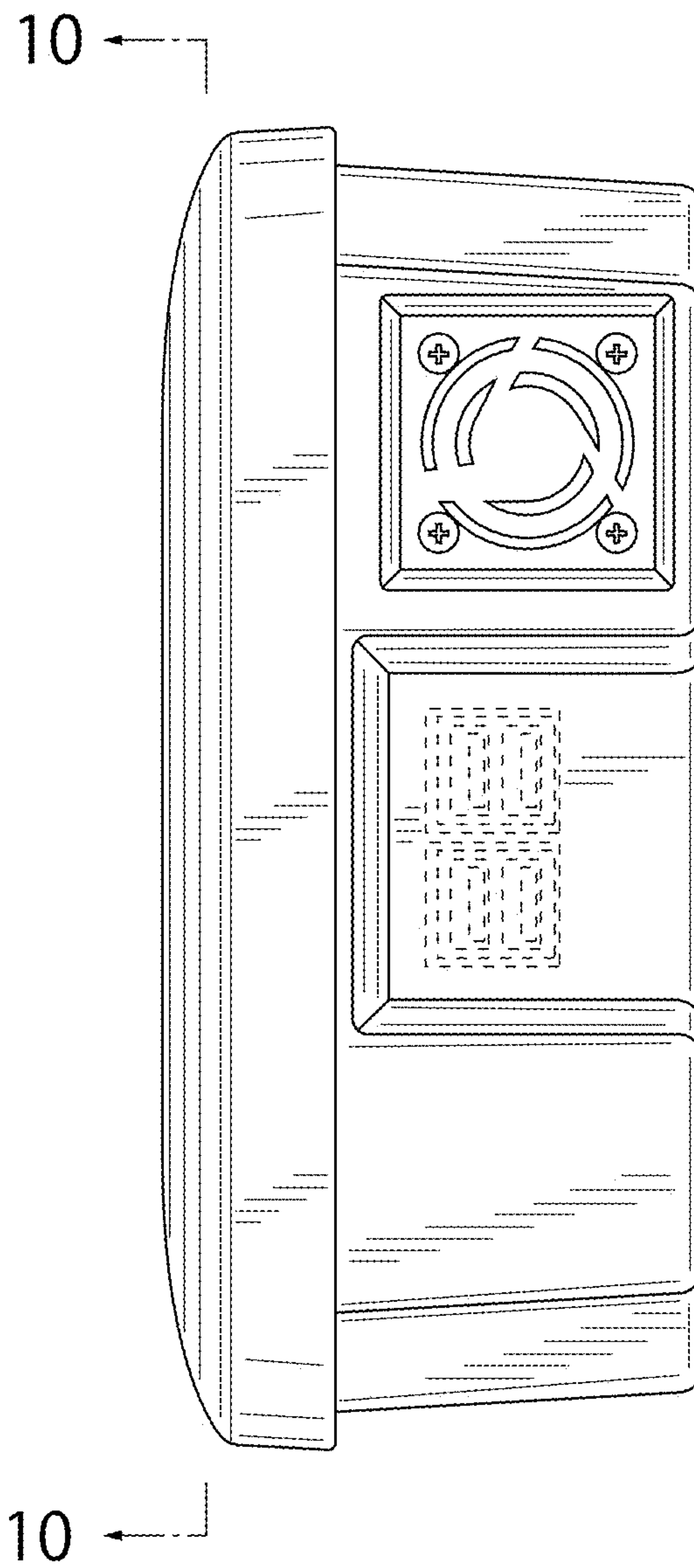


***FIG. 6***

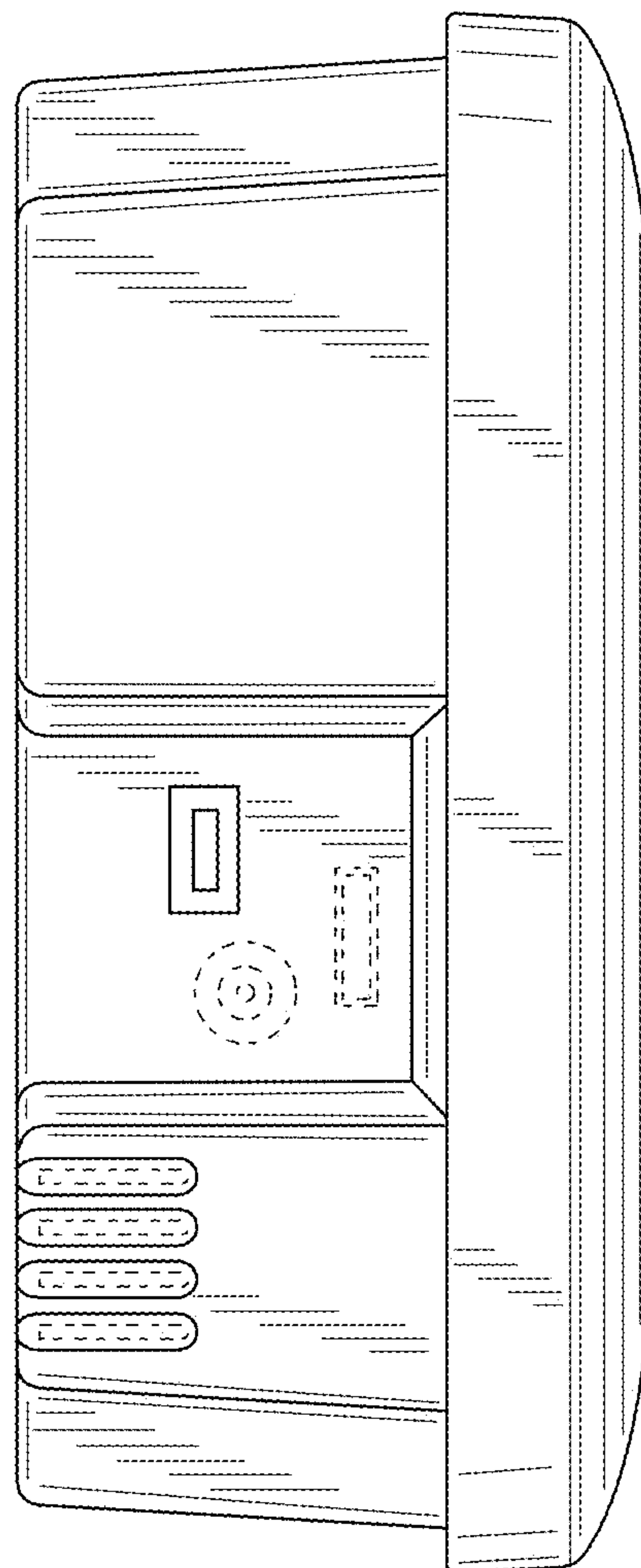




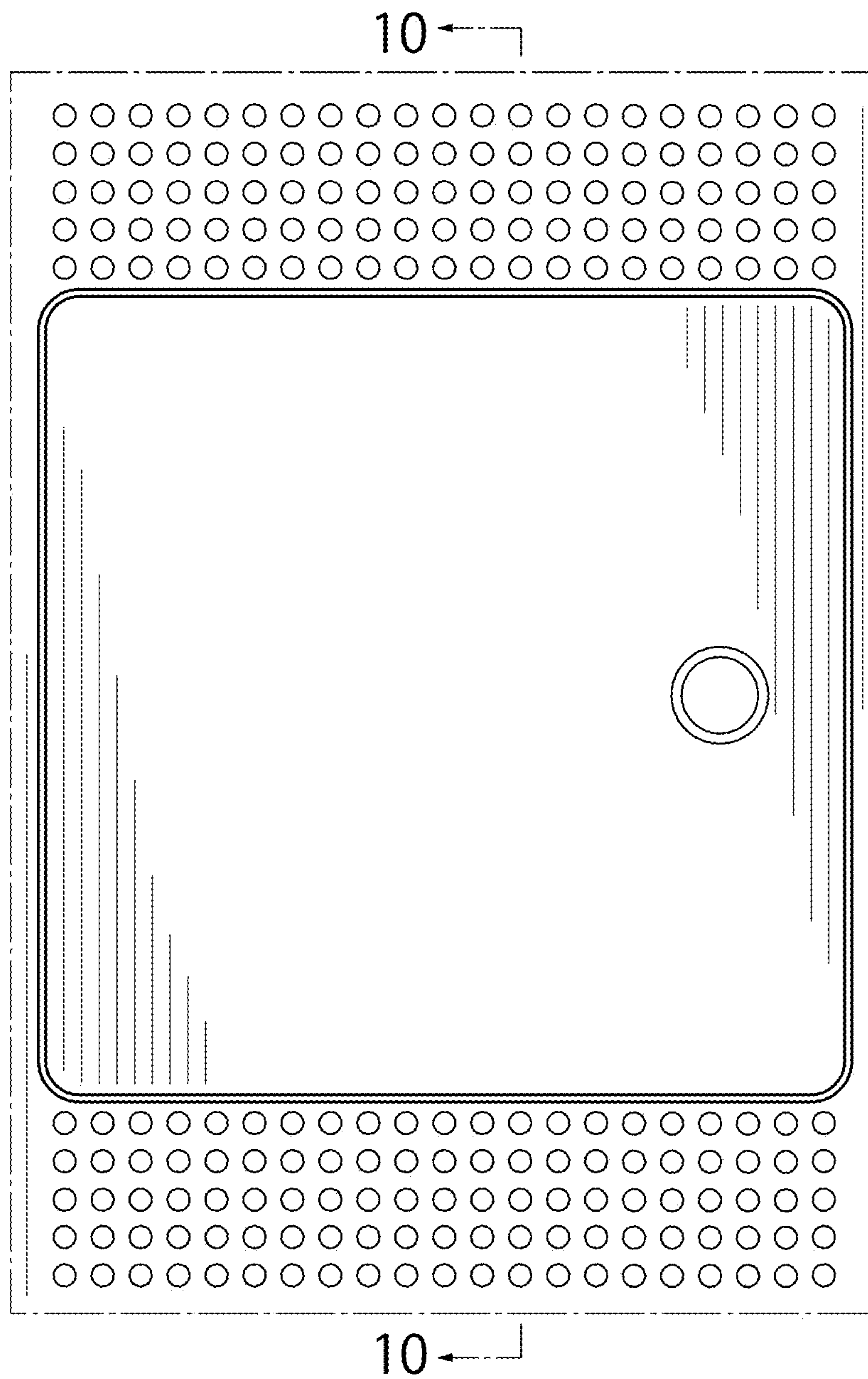
**FIG. 7**



**FIG. 8**



**FIG. 9**



***FIG. 10***

